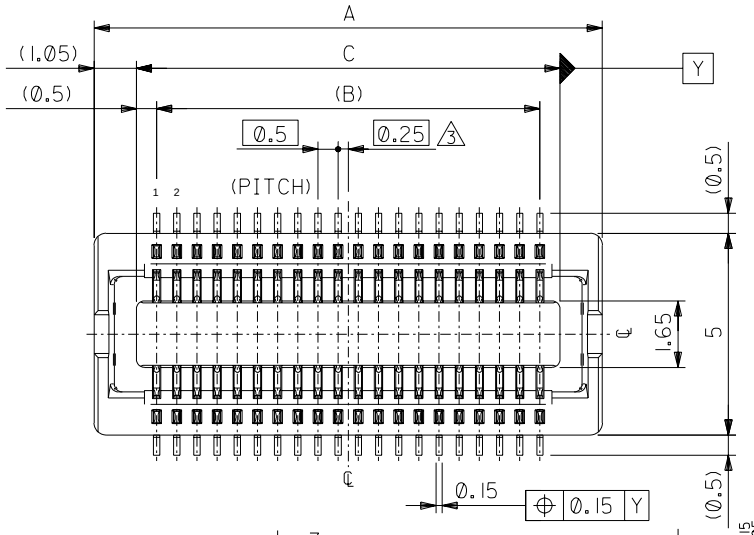
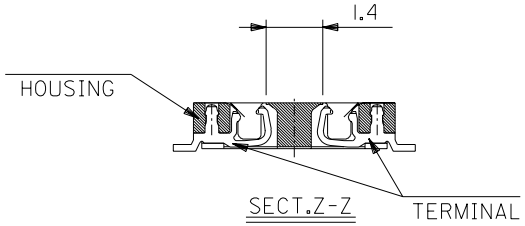
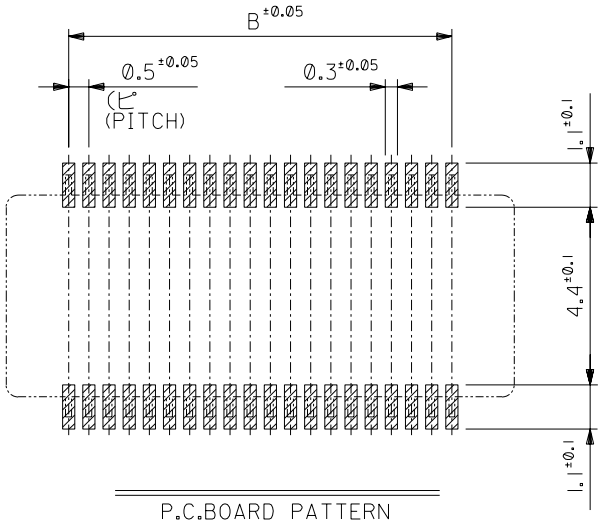
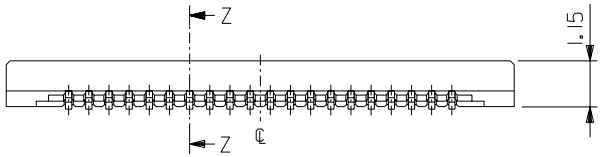
DWG. NO. SD-54722-007

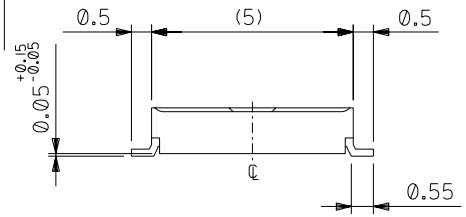




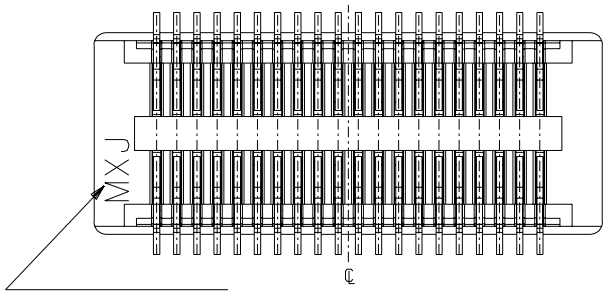


P.C.BOARD PATTERN
DIMENSION. (REF.)
(MOUNTING AREA)





30極以下品形状
SHAPE OF 30CIRCUITS OR LESS



NOTES:

MATERIAL
ハウジング：液晶ポリマー ノ ,UL94V-0

TERMINAL:PHOSPHOR BRONZE(=0.15)
PLATING
¯MUM
GOLD 0.25 MICROMETER MINIMUM.(CONTACT AREA)
0.4 MICROMETER MAXIMUM
GOLD 0.4 MICROMETER MAXIMUM.(TAIL AREA)
1.5 MICROMETER MINIMUM
UNDER PLATING : NICKEL 1.5 MICROMETER MINIMUM

3
APPLY FOR (CIRCUIT/2)=EVEN.
4 嵌合相手：55560 シリーズ, 53794 シリーズ
MATE WITH : 55560 SERIES,53794 SERIES.
5
TAIL COPLANARITY TO BE 0.1 MAXIMUM.

C	B	A	MATERIAL. NO	極数 CIRCUIT
8.0	7.0	10.1	54722-0301	30
6.5	5.5	8.6	54722-0241	24
6.0	5.0	8.1	54722-0221	22
5.5	4.5	7.6	54722-0201	20
4.5	3.5	6.6	54722-0161	16

MODEL NO. 54722-***1

DIMENSIONS: ☐ mm/INCH ☐ INCH/mm ☒ mm ONLY

SHT | REV

REV	DESCRIPTION	MATERIAL 材料	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE	DESIGN UNITS	1st 2nd 3rd ANGLE PROJECTION	1st 2nd REVISE ON CAD ONLY
		注記参照 SEE NOTES	10 UNDER 未満	±0.2	—//—	☒mm ☐INCH		
		FINISH 仕上げ —//—	10 OVER 以上 30 UNDER 未満	±0.25				
		WIRE RANGE 適用電線範囲 —//—	30 OVER 以上	±0.3				
		INS. RANGE 被覆外径 —//—	ANGLE 角度	±3°				

DRAWN BY & DATE	S.AIHARA '00/10/5
CHECKED BY & DATE	M.SASAO '03/03/31
APPROVED BY & DATE	M.SASAO '03/03/31
CAD FILENAME	

TITLE:
0.5 B-To-B Conn
Rec HOUSING Assy (Hgt=1.5mm)

molex MOLEX INCORPORATED

MATERIAL NO. SEE CHART | DRAWING NO. | SHEET NO. 1 OF 2

1st 2nd 3rd 4th

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.

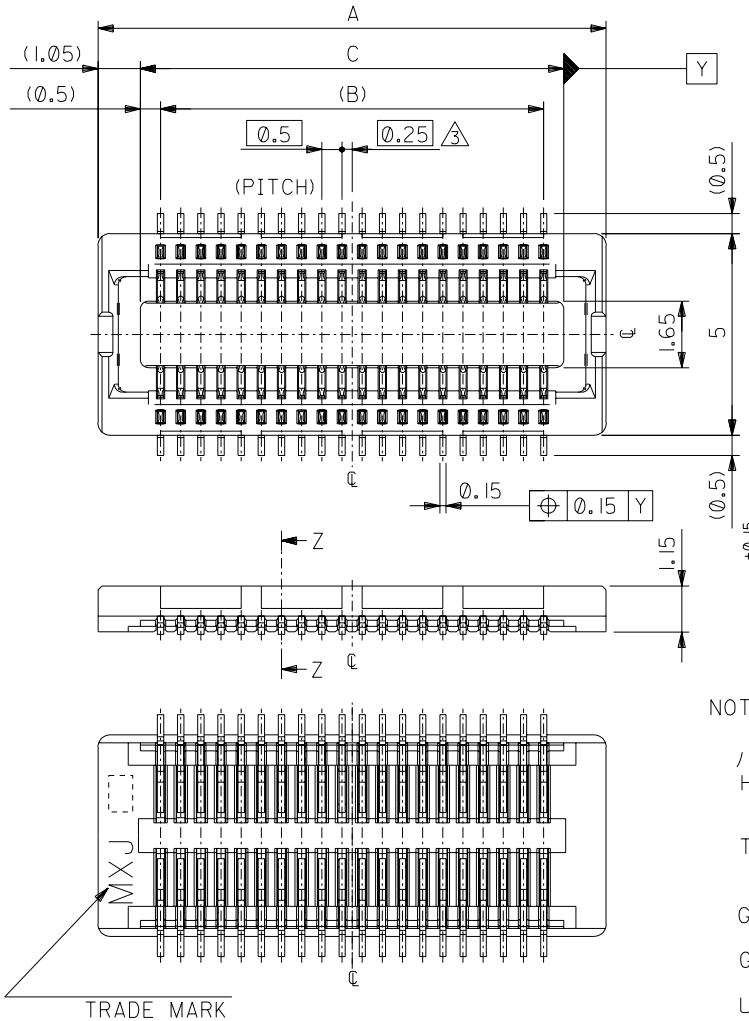
SIZE B

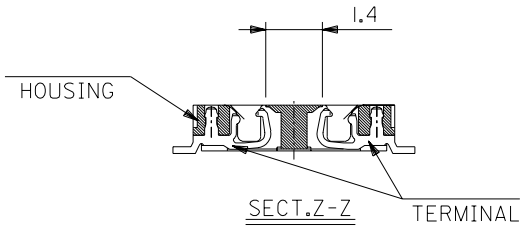
REV	DESCRIPTION	DRWN:	CH'K:	APPR:
G	REVISED 1st 2nd NO. J2003-2517	S.AIHARA '03/03/31	M.SASAO	M.SASAO
F	REVISED 1st 2nd NO. J2003-1929	T.YASUI '03/ 1/23	T.ITO	T.ITO
E	REVISED 1st 2nd NO. J2003-1468	T.YASUI '02/11/25	T.ITO	T.YAMAGUCHI

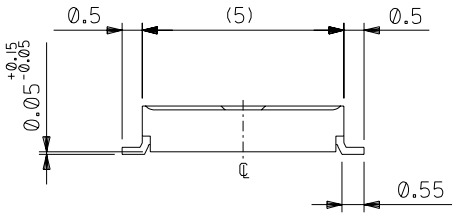
DO NOT SCALE DRAWING

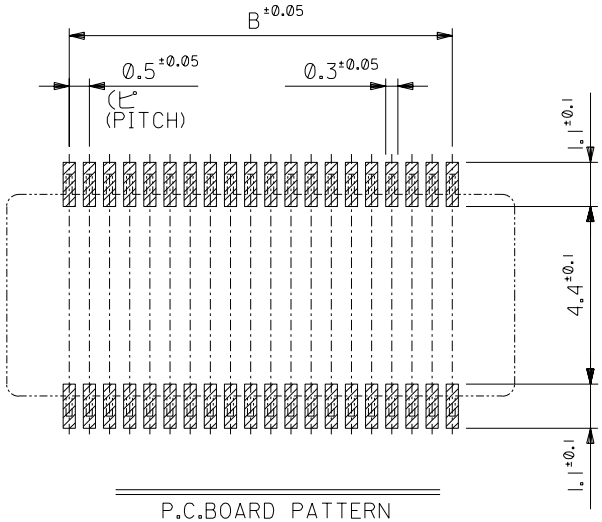
EN-02J(097) MXJ-54

DWG. NO. SD-54722-007









P.C.BOARD PATTERN
DIMENSION. (REF.)
(MOUNTING AREA)

34極以上品形状
SHAPE OF 34CIRCUITS OR MORE

NOTES:

MATERIAL
ハウジング：液晶ポリマー　ガラス充填 ,UL94V-0 (黒)
HOUSING:LIQUID CRYSTRAL POLYMER (GLASS FILLED)
UL94V-0,(COLOR:BLACK)

TERMINAL:PHOSPHOR BRONZE(=0.15)
PLATING
0.25 MICROMETER MINIMUM
GOLD 0.25 MICROMETER MINIMUM. (CONTACT AREA)
0.4 MICROMETER MAXIMUM
GOLD 0.4 MICROMETER MAXIMUM. (TAIL AREA)
1.5 MICROMETER MINIMUM
UNDER PLATING : NICKEL 1.5 MICROMETER MINIMUM

3
APPLY FOR (CIRCUIT/2)=EVEN.
4 嵌合相手：55560 シリーズ, 53794 シリーズ
MATE WITH : 55560 SERIES,53794 SERIES.
5 0.1 MAXIMUM.
TAIL COPLANARITY TO BE 0.1 MAXIMUM.

C	B	A	MATERIAL. NO	極数 CIRCUIT
20.5	19.5	22.6	54722-0801	80
15.5	14.5	17.6	54722-0601	60
13.0	12.0	15.1	54722-0501	50
12.0	11.0	14.1	54722-0461	46
10.5	9.5	12.6	54722-0401	40
9.0	8.0	11.1	54722-0341	34

MODEL NO. 54722-***1

DIMENSIONS: ☐ mm INCH ☐ INCH mm ☒ mm ONLY

SHT | REV

DO NOT SCALE DRAWING

234NO. DRWN: CH'K: APPR:	233NO. DRWN: CH'K: APPR:	232NO. DRWN: CH'K: APPR:	231NO. DRWN: CH'K: APPR:	REVISED 230NO. J2003-2517 DRWN: S.AIHARA '03/03/31 CH'K: M.SASAO APPR: M.SASAO	DESCRIPTION
				G	REV

MATERIAL 材料: 注記参照 SEE NOTES

FINISH 仕上げ: —//—

WIRE RANGE 適用電線範囲: —//—

INS. RANGE 被覆外径: —//—

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差

10 UNDER 未満	±0.2
10 OVER 以上 30 UNDER 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°

SCALE —//—

DESIGN UNITS ☒mm ☐INCH

229 THIRD ANGLE PROJECTION

227 REVISE ON CAD ONLY

DRAWN BY & DATE: S.AIHARA '01/02/13

CHECKED BY & DATE: M.SASAO '03/03/31

APPROVED BY & DATE: M.SASAO '03/03/31

TITLE: 0.5 B-To-B Conn Rec HOUSING Assy (Hgt=1.5mm)

molex MOLEX INCORPORATED

CAD FILENAME: 54722007.S02

MATERIAL NO.: SEE CHART

DRAWING NO.: SD-54722-007

SHEET NO.: 2 OF 2

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SIZE: B

17.S02

EN-02J(097) MXJ-54